



40V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _A = 25°C
-40V	50mΩ @ V _{GS} = -10V	-6.0A
	79mΩ @ V _{GS} = -4.5V	-4.7A

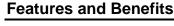
Description and Applications

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor control
- Backlighting
- DC-DC Converters
- Power management functions

SO-8

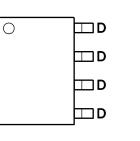
Top View



- Low on-resistance
- Fast switching speed
- "Green" component and RoHS compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See diagram below
- Terminals: Finish Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Weight: 0.074 grams (approximate)



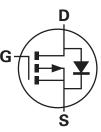
Top View

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Equivalent Circuit

Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMP4050SSS-13	P4050SS	13	12	2,500

Note: 1. Diodes, Inc. defines "Green" products as those which are RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.

Marking Information



DII = Manufacturer's Marking
P4050SS = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 09 = 2009)
WW = Week (01-53)



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit	
Drain-Source voltage			V _{DSS}	-40	V	
Gate-Source voltage (Note 2)			V _{GS}	±20	V	
Continuous Drain current		(Note 4)		-6.0		
	$V_{GS} = 10V$	$T_A = 70^{\circ}C$ (Note 4)	ID	-4.8	А	
		(Note 3)		-4.4		
Pulsed Drain current V _{GS} = 10V (Note 5)		(Note 5)	I _{DM}	-27.0	A	
Continuous Source current (Body diode)		(Note 4)	I _S	-4.0	А	
Pulsed Source current (Body diode)		(Note 5)	I _{SM}	-27.0	А	

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit		
Power dissipation	(Note 3)		1.56 12.5	W	
Linear derating factor	(Note 4)		2.8 22.5	mW/°C	
Thermal Resistance, Junction to Ambient	(Note 3) (Note 4)		80 44.5	°C/W	
Thermal Resistance, Junction to Lead	(Note 6)	R _{θJL}	35		
Operating and storage temperature range		TJ, TSTG	-55 to 150	°C	

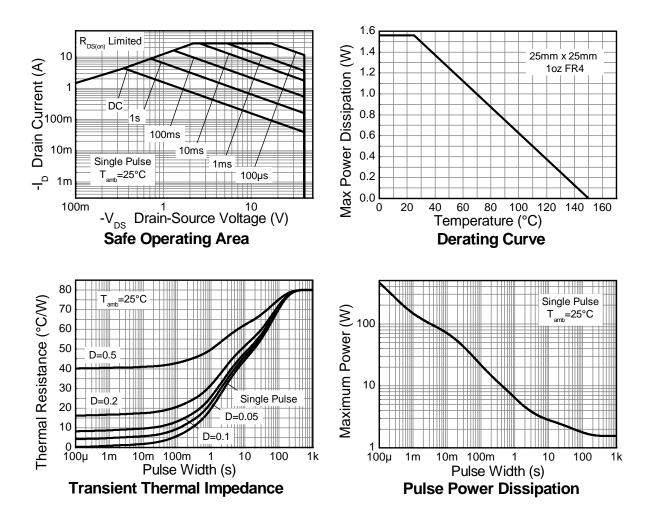
Notes: 2. AEC-Q101 V_{GS} maximum is $\pm 16V.$

3. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

4. Same as note (3), except the device is measured with D= 0.02 and pulse width 300 μ s. The pulse current is limited by the maximum junction temperature. 6. Thermal resistance from junction to solder-point (at the end of the drain lead).



Thermal Characteristics





Electrical Characteristics @T_A = 25°C unless otherwise specified

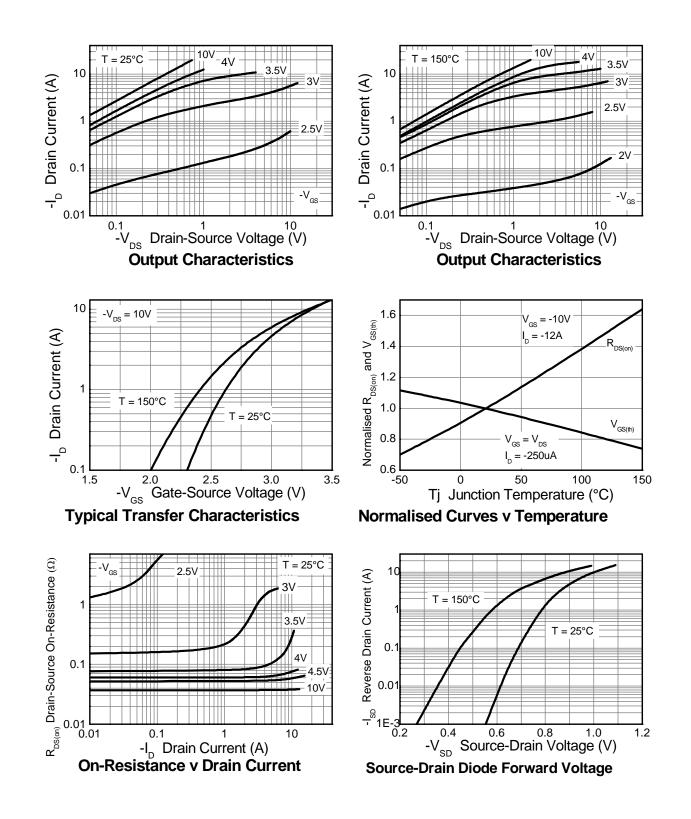
Characteristic	Symbol	Min	Тур	Мах	Unit	Test Condition	
OFF CHARACTERISTICS	Symbol	WIIII	тур	Wax	Onit	Test condition	
Drain-Source Breakdown Voltage	BV _{DSS}	-40	_		V	I _D = -250μA, V _{GS} = 0V	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-0.5	μA	V_{DS} = -40V, V_{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	V _{GS} = ±20V, V _{DS} = 0V	
ON CHARACTERISTICS	000						
Gate Threshold Voltage	V _{GS(th)}	-1.0	_	-3.0	V	I _D = -250μA, V _{DS} = V _{GS}	
			0.038	0.050	0	V _{GS} = -10V, I _D = -6A	
Static Drain-Source On-Resistance (Note 7)	R _{DS} (ON)	_	0.055	0.079	Ω	V _{GS} = -4.5V, I _D = -5A	
Forward Transconductance (Notes 7 & 8)			14		S	V _{DS} = -15V, I _D = -6A	
Diode Forward Voltage (Note 7)	V _{SD}	_	-0.86	-1.2	V	I _S = -6A, V _{GS} = 0V	
Reverse recovery time (Note 8)	t _{rr}		18.5		ns	-I _S = -2.5, di/dt= 100Α/μs	
Reverse recovery charge (Note 8)	Q _{rr}	_	15.6		nC		
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	674		pF	N 00)/ N 0)/	
Output Capacitance	C _{oss}	_	115		pF	V _{DS} = -20V, V _{GS} = 0V f= 1MHz	
Reverse Transfer Capacitance	C _{rss}	_	67.7		pF		
Total Gate Charge (Note 9)	Qg	_	6.9	_	nC	V _{GS} = -4.5V	
Total Gate Charge (Note 9)	Qg	_	13.9		nC	V _{DS} = -20V	
Gate-Source Charge (Note 9)	Q _{gs}		2		nC	V _{GS} = -10V I _D = -6A	
Gate-Drain Charge (Note 9)	Q _{qd}	_	3.4		nC	7	
Turn-On Delay Time (Note 9)	t _{D(on)}		1.9		ns		
Turn-On Rise Time (Note 9)	tr	_	3.1		ns	V _{DD} = -20V, V _{GS} = -10V	
Turn-Off Delay Time (Note 9)	t _{D(off)}		31.5		ns	I_D = -1A, $R_G \cong 6.0\Omega$	
Turn-Off Fall Time (Note 9)	t _f		12.6		ns		

Notes:

Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
 For design aid only, not subject to production testing.
 Switching characteristics are independent of operating junction temperatures.

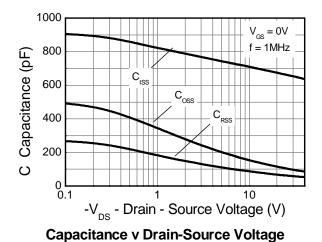


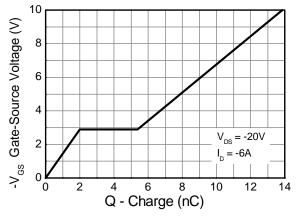
Typical Characteristics





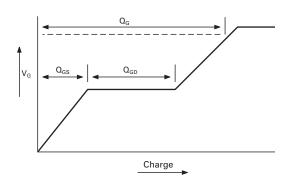
Typical Characteristics - continued



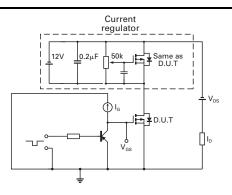


Gate-Source Voltage v Gate Charge

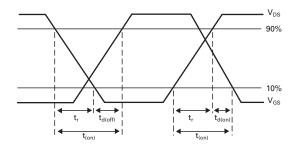
Test Circuits



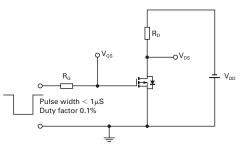
Basic gate charge waveform



Gate charge test circuit



Switching time waveforms

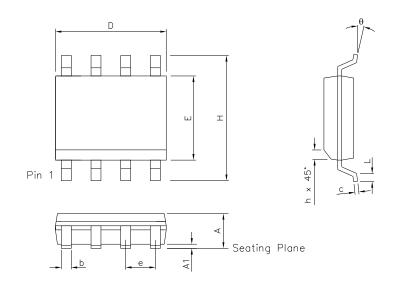


Switching time test circuit

DMP4050SSS Document Number DS32108 Rev 1 - 2 Downloaded from <u>Elcodis.com</u> electronic components distributor

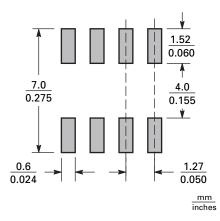


Package Outline Dimensions



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
А	0.053	0.069	1.35	1.75	е	0.050 BSC		1.27 BSC	
A1	0.004	0.010	0.10	0.25	b	0.013	0.020	0.33	0.51
D	0.189	0.197	4.80	5.00	С	0.008	0.010	0.19	0.25
Н	0.228	0.244	5.80	6.20	θ	0°	8°	0°	8°
E	0.150	0.157	3.80	4.00	h	0.010	0.020	0.25	0.50
L	0.016	0.050	0.40	1.27	-	-	-	-	-

Suggested Pad Layout





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